

Usage Data Sheet

Product: Insat Epoxy Glue Remover

Uses: For removing various resin-based coatings and underfills from PCBs.

Method of Use: Apply the product generously on the target area. If a small amount is applied, the volatile ingredients will evaporate before they can work on the resin coating, therefore a thick coating of the product is best.

The product can be applied using a suitable instrument or be brushed on.

Ensure the work area is adequately ventilated. Wear protective gloves as this product can cause skin irritation. Wash hands thoroughly if the product comes into contact with your skin.

The time taken to remove the resin-based glue will depend on the thickness and type of the resin-glue. The longer the product is allowed to work, the better the results may be. Typically with underfill resin-glue, allow at least 30 minutes before attempting to remove the residual resin-glue.